www.ti.com

SLOS073E-MARCH 1976-REVISED FEBRUARY 2006

#### **FEATURES**

- Continuous Short-Circuit Protection
- Wide Common-Mode and Differential Voltage Ranges
- No Frequency Compensation Required
- Low Power Consumption
- No Latch-Up
- Unity-Gain Bandwidth . . . 3 MHz Typ
- Gain and Phase Match Between Amplifiers
- Low Noise . . . 8 nV/√Hz Typ at 1 kHz

#### 

### **DESCRIPTION/ORDERING INFORMATION**

The RC4558 device is a dual general-purpose operational amplifier, with each half electrically similar to the  $\mu$ A741, except that offset null capability is not provided.

The high common-mode input voltage range and the absence of latch-up make this amplifier ideal for voltage-follower applications. The device is short-circuit protected, and the internal frequency compensation ensures stability without external components.

#### ORDERING INFORMATION

T <sub>A</sub>	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	MSOP/VSSOP - DGK	Reel of 2500	RC4558DGKR	YR_ <sup>(2)</sup>
	PDIP – P	Tube of 50	RC4558P	RC4558P
	SOIC - D	Tube of 75	RC4558D	RC4558
0°C to 70°C	30IC - D	Reel of 2500	RC4558DR	RC4000
	SOP - PS	Reel of 2000	RC4558PSR	R4558
	TSSOP – PW	Tube of 150	RC4558PW	R4558
	1330F - FW	Reel of 2000	RC4558PWR	K4000
	MSOP/VSSOP - DGK	Reel of 2500	RC4558IDGKR	YS_ <sup>(2)</sup>
	PDIP – P	Tube of 50	RC4558IP	RC4558IP
–40°C to 85°C	SOIC - D	Tube of 75	RC4558ID	R4558I
-40°C 10 85°C	30IC - D	Reel of 2500	RC4558IDR	K4000I
	TOOD DW	Tube of 150	RC4558IPW	R4558I
	TSSOP – PW	Reel of 2000	RC4558IPWR	1000H

<sup>(1)</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

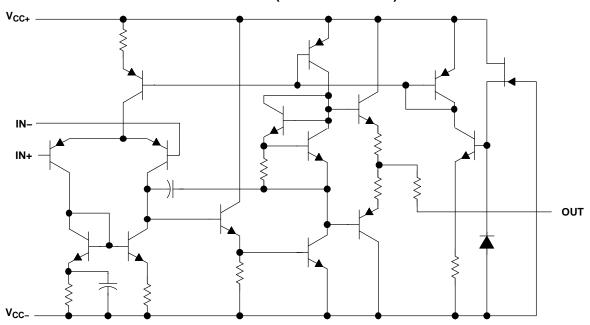
(2) The actual top-side marking has one additional character that designates the assembly/test site.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



# SCHEMATIC (EACH AMPLIFIER)



# RC4558 DUAL GENERAL-PURPOSE OPERATIONAL AMPLIFIER

SLOS073E-MARCH 1976-REVISED FEBRUARY 2006

# Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{CC+}$	Supply voltage <sup>(2)</sup>			18	V
V <sub>CC</sub> -	Supply voltage (-)			-18	V
$V_{ID}$	Differential input voltage (3)		±30	V	
VI	Input voltage (any input) <sup>(2)(4)</sup>		±15	V	
	Duration of output short circuit to ground, one amplifier at a time (5)	Un	limited		
		D package		97	
	Package thermal impedance (6) (7)	DGK package		172	
$\theta_{JA}$		P package		85	°C/W
		PS package	9		
		PW package		149	
T <sub>J</sub>	Operating virtual junction temperature			150	°C
T <sub>stg</sub>	Storage temperature range		-65	150	°C

<sup>(1)</sup> Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltage values, unless otherwise noted, are with respect to the midpoint between V<sub>CC+</sub> and V<sub>CC-</sub>.

(3) Differential voltages are at IN+ with respect to IN-.

(4) The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 V, whichever is less.

(5) Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.

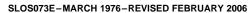
(7) The package thermal impedance is calculated in accordance with JESD 51-7.

### **Recommended Operating Conditions**

			MIN	MAX	UNIT
V <sub>CC+</sub>	Supply voltage		5	15	V
V <sub>CC</sub> -	Supply vollage				V
_	Operating free air temperature	RC4558	0	70	°C
1A	Operating free-air temperature	RC4558I	-40	85	30

<sup>(6)</sup> Maximum power dissipation is a function of  $T_J$  (max),  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J \text{ (max)} - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.

# **RC4558 DUAL GENERAL-PURPOSE OPERATIONAL AMPLIFIER**





### **Electrical Characteristics**

at specified free-air temperature,  $V_{CC+}$  = 15 V,  $V_{CC-}$  = -15 V

	PARAMETER		TEST CONDITIONS <sup>(1)</sup>	T <sub>A</sub> <sup>(2)</sup>	MIN	TYP	MAX	UNIT	
V	Innut effect voltage		V <sub>O</sub> = 0	25°C		0.5	6	mV	
$V_{IO}$	Input offset voltage	v <sub>0</sub> = 0		Full range			7.5	IIIV	
	land offert coment		V 0	25°C		5	200	- 0	
I <sub>IO</sub>	Input offset current		$V_O = 0$	Full range			300	nA	
	lanut biog gurrant		V 0	25°C		150	500	nA	
I <sub>IB</sub>	Input bias current		$V_O = 0$	Full range			800	ΠA	
V <sub>ICR</sub>	Common-mode input voltage range	!		25°C	±12	±14		V	
			$R_L = 10 \text{ k}\Omega$	25°C	±12	±14			
$V_{OM}$	Maximum output voltage swing		D 210	25°C	±10	±13		V	
		$R_L = 2 k\Omega$	Full range	±10					
^	Large-signal differential voltage amplification		$R_L \ge k\Omega$ ,	25°C	20	300		V/mV	
A <sub>VD</sub>	Large-signal differential voltage am	$V_O = \pm 10 \text{ V}$		Full range	15			V/MV	
B <sub>1</sub>	Unity-gain bandwith			25°C		3		MHz	
rį	Input resistance			25°C	0.3	5		ΜΩ	
CMRR	Common-mode rejection ratio			25°C	70	90		dB	
k <sub>SVS</sub>	Supply-voltage sensitivity ( $\Delta V_{IO}/\Delta V_{CC}$ )		$V_{CC} = \pm 15 \text{ V}$ to $\pm 9 \text{ V}$	25°C		30	150	μV/V	
V <sub>n</sub>	Equivalent input noise voltage (closed loop)		$A_{VD} = 100,$ $R_{S} = 100 \Omega,$ $f = 1 \text{ kHz},$ $BW = 1 \text{ Hz}$	25°C		8		nV/√ <del>Hz</del>	
				25°C		2.5	5.6		
I <sub>CC</sub>	Supply current (both amplifiers)		V <sub>O</sub> = 0, No load	T <sub>A</sub> min		3	6.6	mA	
			140 load	T <sub>A</sub> max		2.3	5		
			$V_{O} = 0$ ,	25°C		75	170		
$P_D$	Total power dissipation (both amplit	Total power dissipation (both amplifiers)		T <sub>A</sub> min		90	200	mW	
			No load	T <sub>A</sub> max		70	150		
V	Crosstalk attenuation	Open loop	$R_S = 1 k\Omega$ ,	25°C		85		dB	
$V_{O1}/V_{O2}$	Crossiaik atteriuation	A <sub>VD</sub> = 100	f = 10 kHz	20.0		105		ub	

All characteristics are measured under open-loop conditions with zero common-mode input voltage, unless otherwise specified. Full range is  $0^{\circ}$ C to  $70^{\circ}$ C for RC4558 and  $-40^{\circ}$ C to  $85^{\circ}$ C for RC4558I.

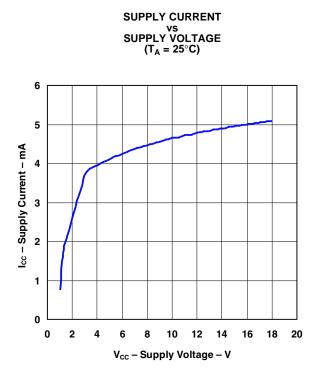
# **Operating Characteristics**

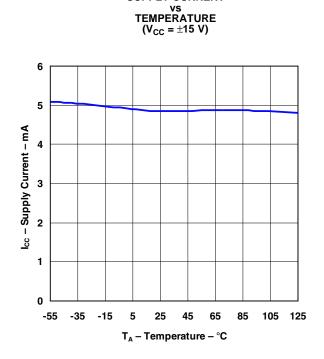
 $V_{CC+}$  = 15 V,  $V_{CC-}$  = -15 V,  $T_A$  = 25°C

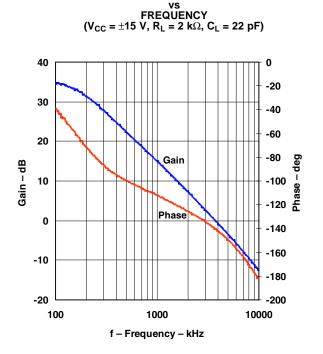
	PARAMETER		MIN	TYP	MAX	UNIT		
t <sub>r</sub>	Rise time	$V_I = 20 \text{ mV},$	$R_L = 2 k\Omega$ ,	$C_{L} = 100 \text{ pF}$		0.13		ns
	Overshoot	V <sub>I</sub> = 20 mV,	$R_L = 2 k\Omega$ ,	C <sub>L</sub> = 100 pF		5		%
SR	Slew rate at unity gain	V <sub>I</sub> = 10 V,	$R_L = 2 k\Omega$ ,	C <sub>L</sub> = 100 pF	1.1	1.7		V/µs

SUPPLY CURRENT

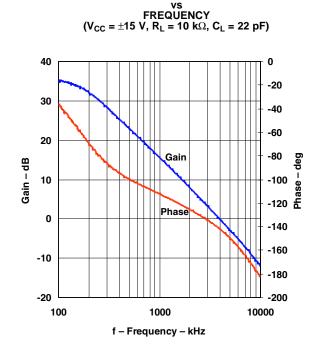
### TYPICAL CHARACTERISTICS







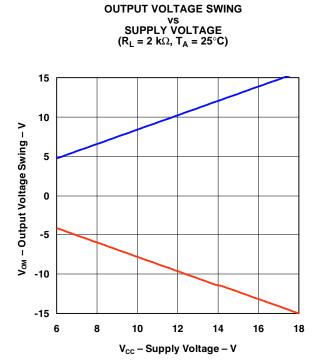
**GAIN AND PHASE** 

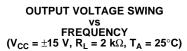


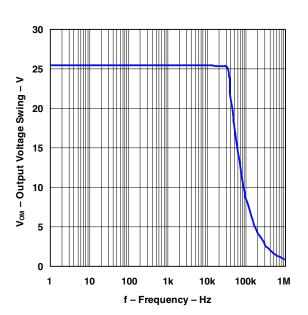
**GAIN AND PHASE** 



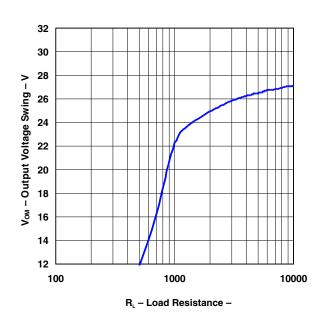
### **TYPICAL CHARACTERISTICS (continued)**



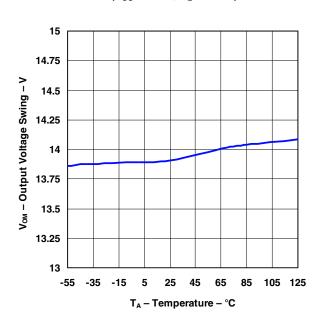




OUTPUT VOLTAGE SWING VS LOAD RESISTANCE ( $V_{CC} = \pm 15 \text{ V}, T_A = 25^{\circ}\text{C}$ )

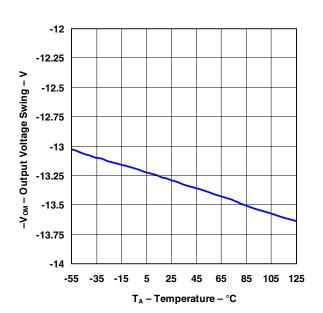


OUTPUT VOLTAGE SWING VS TEMPERATURE (V<sub>CC</sub> =  $\pm 15$  V, R<sub>L</sub> = 10 k $\Omega$ )

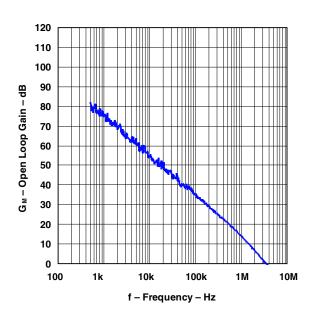


# **TYPICAL CHARACTERISTICS (continued)**

**NEGATIVE OUTPUT VOLTAGE SWING** 

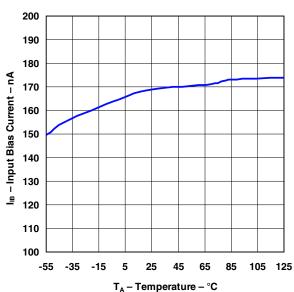


 $\begin{array}{c} \text{OPEN LOOP GAIN} \\ \text{Vs} \\ \text{FREQUENCY} \\ \text{(V}_{\text{CC}} = \pm 15 \text{ V, R}_{L} = 2 \text{ k}\Omega, \text{ C}_{L} = 22 \text{ pF, T}_{A} = 25^{\circ}\text{C)} \end{array}$ 

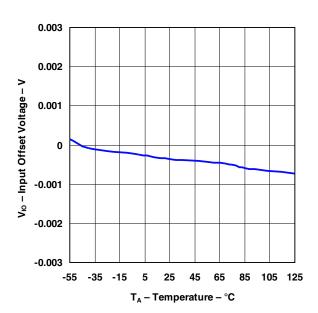


INPUT BIAS CURRENT vs TEMPERATURE

(V<sub>CC</sub> = ±15 V)

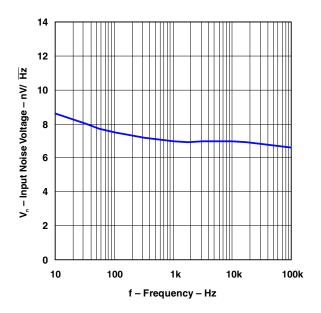


INPUT OFFSET VOLTAGE
vs
TEMPERATURE
(V<sub>CC</sub> = ±15 V)





# **TYPICAL CHARACTERISTICS (continued)**





### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
RC4558D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4558DE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4558DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4558DGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4558DGKRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4558DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4558DRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4558DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4558ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4558IDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4558IDGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4558IDGKRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4558IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4558IDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4558IP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
RC4558IPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
RC4558IPW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4558IPWE4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4558IPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4558IPWRE4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4558P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
RC4558PE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
RC4558PSLE	OBSOLETE	SO	PS	8		TBD	Call TI	Call TI
RC4558PSR	ACTIVE	SO	PS	8	2000	Green (RoHS &		Level-1-260C-UNLIM
RC4558PSRE4	ACTIVE	so	PS	8	2000	no Sb/Br)		Level-1-260C-UNLIM



#### PACKAGE OPTION ADDENDUM

6-Dec-2006

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
RC4558PW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4558PWE4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4558PWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI
RC4558PWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4558PWRE4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4558PWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC4558Y	OBSOLETE	XCEPT	Υ	0		TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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### P (R-PDIP-T8)

#### PLASTIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg\_info.htm

# DGK (S-PDSO-G8)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
- E. Falls within JEDEC MO-187 variation AA, except interlead flash.



# D (R-PDSO-G8)

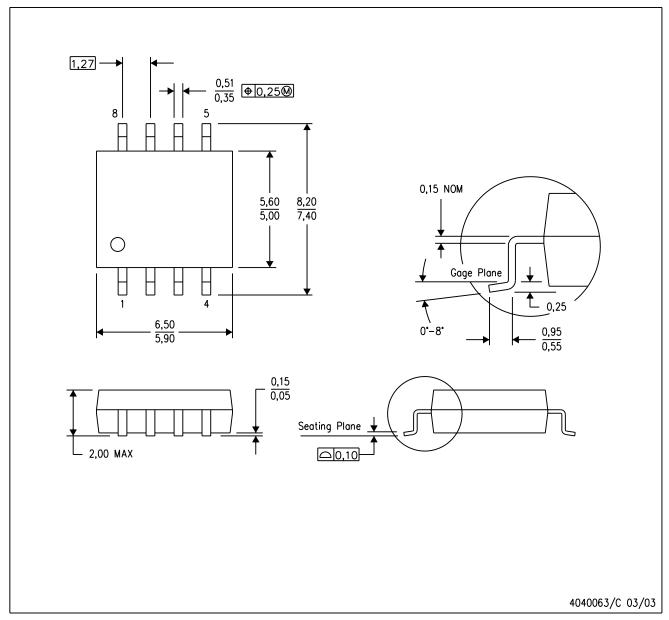
# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AA.





NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



### PW (R-PDSO-G\*\*)

### 14 PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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